

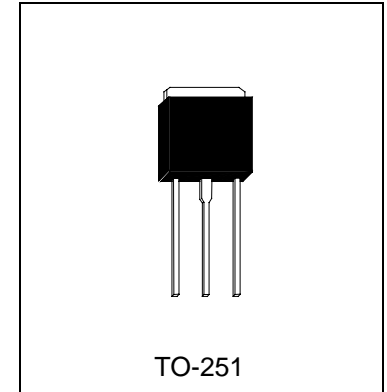


HI669A

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HI669A is designed for low frequency power amplifier.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C
- Maximum Power Dissipation
 - Total Power Dissipation (Tc=25°C) 1 W
- Maximum Voltages and Currents
 - BVCBO Collector to Base Voltage 180 V
 - BVCEO Collector to Emitter Voltage 160 V
 - BVEBO Emitter to Base Voltage 5 V
 - IC Collector Current 1.5 A

Characteristics (Ta=25°C)

DataSheet4U.com

DataShe

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	180	-	-	V	IC=1mA
BVCEO	160	-	-	V	IC=10mA
BVEBO	5	-	-	V	IC=1mA
ICBO	-	-	10	uA	VCB=160V
*VCE(sat)	-	-	1	V	IC=500mA, IB=50mA
*VBE(on)	-	-	1.5	V	VCE=5V, IC=150mA
*hFE1	60	-	200		VCE=5V, IC=150mA
*hFE2	30	-	-		VCE=5V, IC=500mA
fT	-	140	-	MHz	VCE=5V, IC=500mA
Cob	-	14	-	pF	VCB=10V, f=1MHz, IE=0

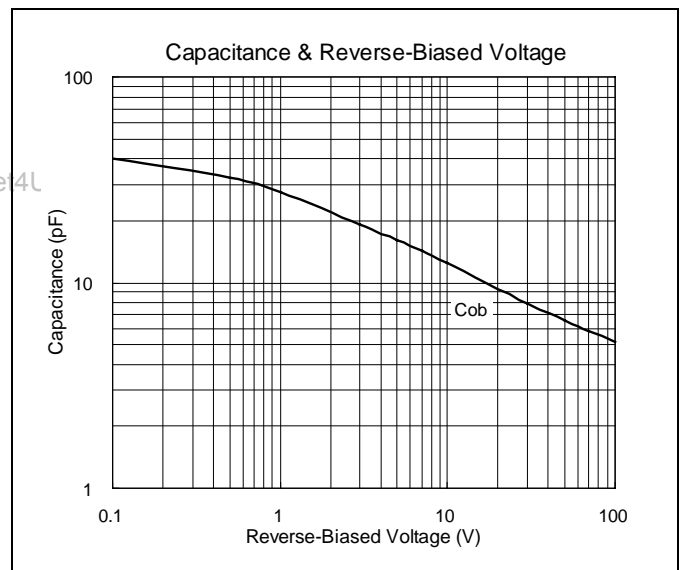
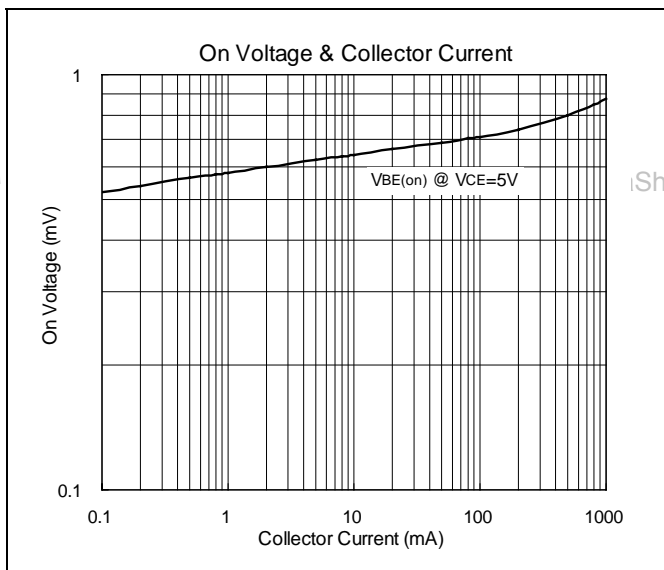
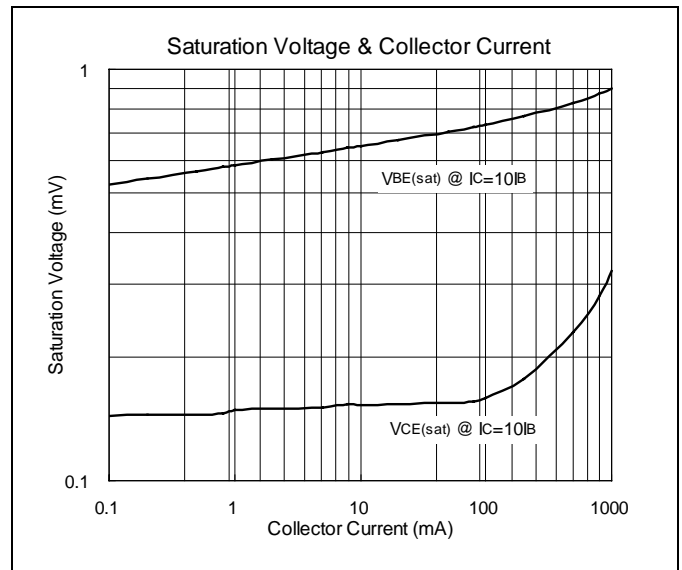
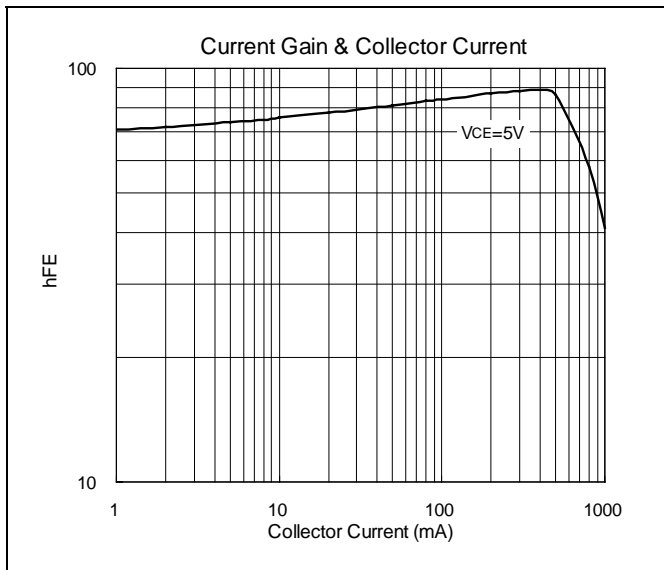
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

Classification Of hFE1

Rank	B	C	D
Range	60-120	100-200	180-320



Characteristics Curve

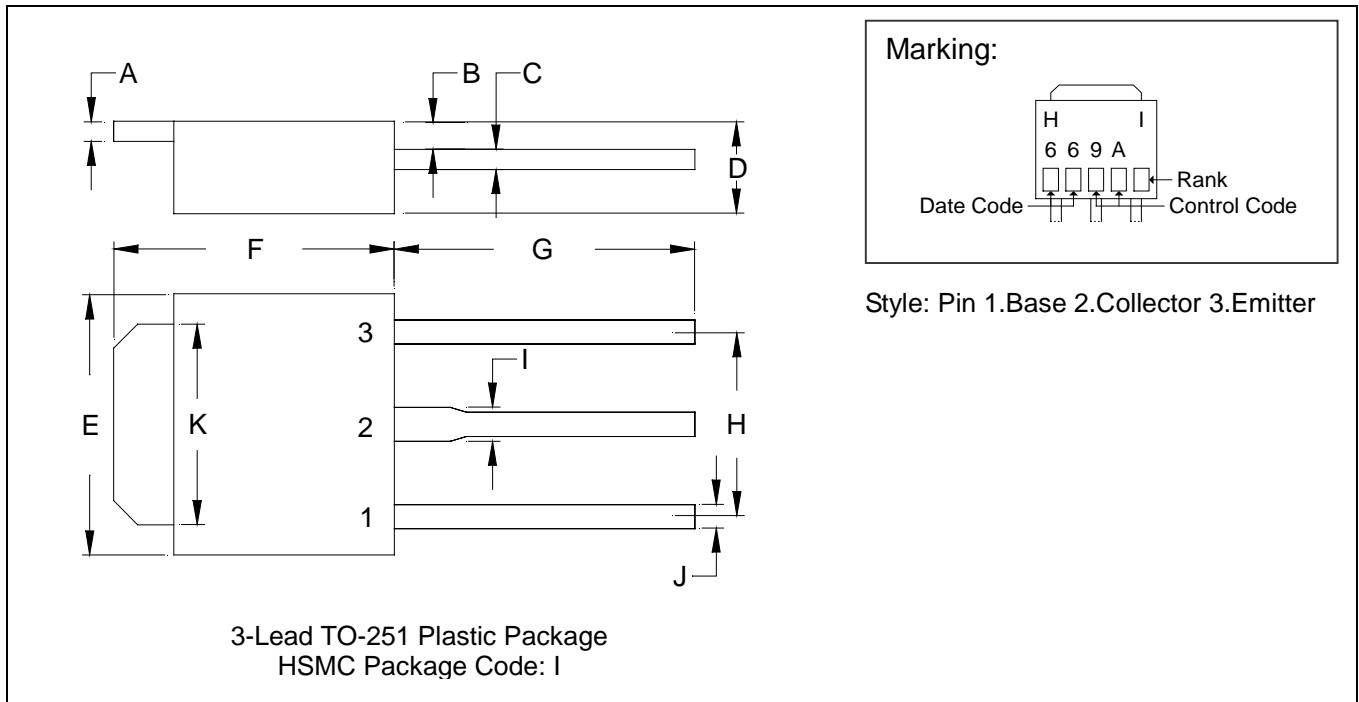




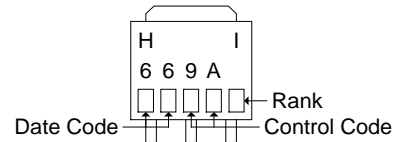
HI-SINCERITY MICROELECTRONICS CORP.

Spec. No. : HE9004
 Issued Date : 1998.01.25
 Revised Date : 2002.09.16
 Page No. : 3/3

TO-251 Dimension



Marking:



Style: Pin 1.Base 2.Collector 3.Emitter

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

- Notes: 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel: 886-3-5983621~5 Fax: 886-3-5982931